Test Items	Test Method	Test Condition	Unit	Typical Value
Tg	IPC-TM-650 2.4.24.4	DMA	℃	185
	IPC-TM-650 2.4.25D	DSC		180
Td	IPC-TM-650 2.4.24.6	TGA (5% W.L)	℃	355
T288	IPC-TM-650 2.4.24.1	TMA		

Autolad3B PREPREG

(UL ANSI: FR-4.0) Bonding Prepreg for Autolad3

PREPREG PARAMETERS

Glass fabric type	Resin content (%)	Cured thickness (mm)	Standard size (Roll type)
106	73	0.050	1.260m×150m
	77	0.060	
1080/1078	64	0.072	1.260m×300m
	69	0.086	
1080	72	0.097	
1086	63	0.076	
3313	56	0.096	
	58	0.102	
2116	54	0.117	1.260m×250m
	57	0.127	
	60	0.139	
1506	46	0.150	1.260m×150m
	48	0.160	
7628	45	0.190	
	47	0.200	
	50	0.215	
	52	0.226	

Other type, resin content and size could be available upon request.

HOT PRESSING CYCLE

- The heat-up rate depends on the inner copper or the structure of multilayer PCB.
- Curing time: >60min (185~195℃).
- If you need any more detail information, please turn to Shengyi Technology Co., Ltd.

STORAGE CONDITION

- 3 months when stored at < 23℃ and <50% RH.
- 6 months when stored at <5℃. Normalize in room temperature for at least 4h before using.
- Beware of moisture, always keep wrapped in damp-proof material. Keeping in normal condition, prepreg might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.

PURCHASING INFORMATION

Thickness	Copper foil	Standard size
0.05 mm to 3.2mm	12um to 105 um	1,020mm 1,070mm

Remarks: Other sheet size and thickness could be available upon request.